

FIG. 1

Diagram IIA' shows a cross-sectional view of the device after the second etching process. The second conductive layer 220 is now patterned into two rectangular blocks, 228 and 229. The first conductive layer 222 is exposed in the recessed areas between these blocks. The second conductive layer 220 is thicker than the first. The first conductive layer 222 is shown as a thin layer. The substrate 240 is at the bottom. The labels 220, 222, 228, 229, 230, 250, and 240 are present. The label IIA' is on the right side.

FIG. 2

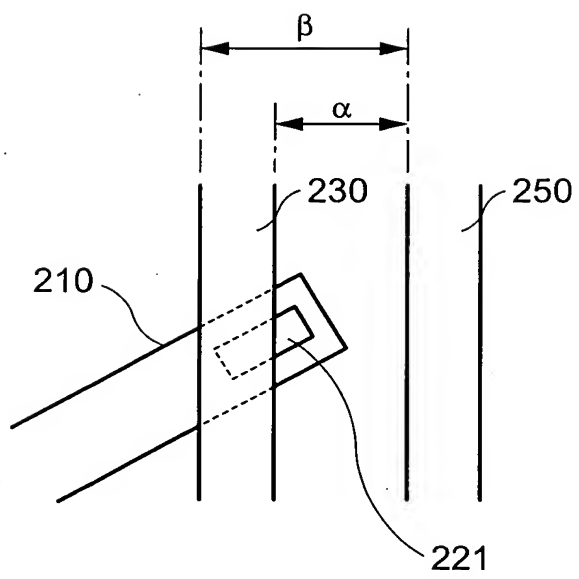


FIG. 3

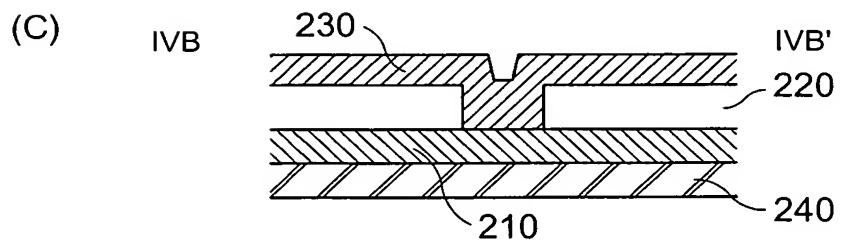
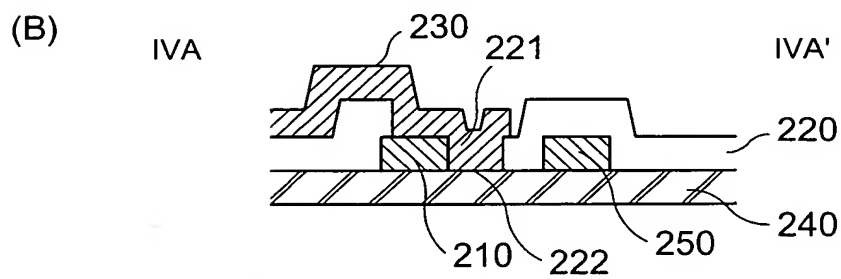
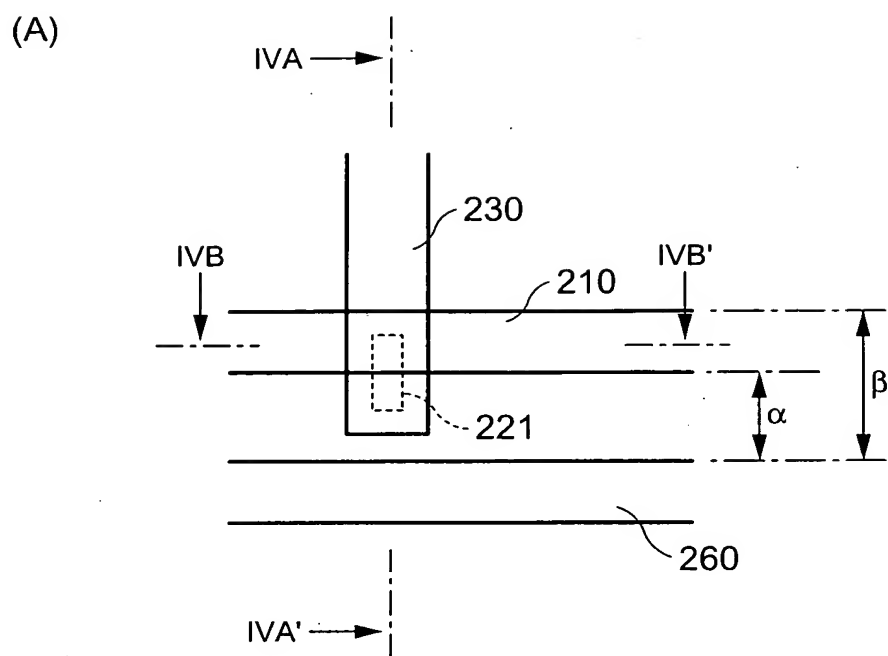


FIG. 4

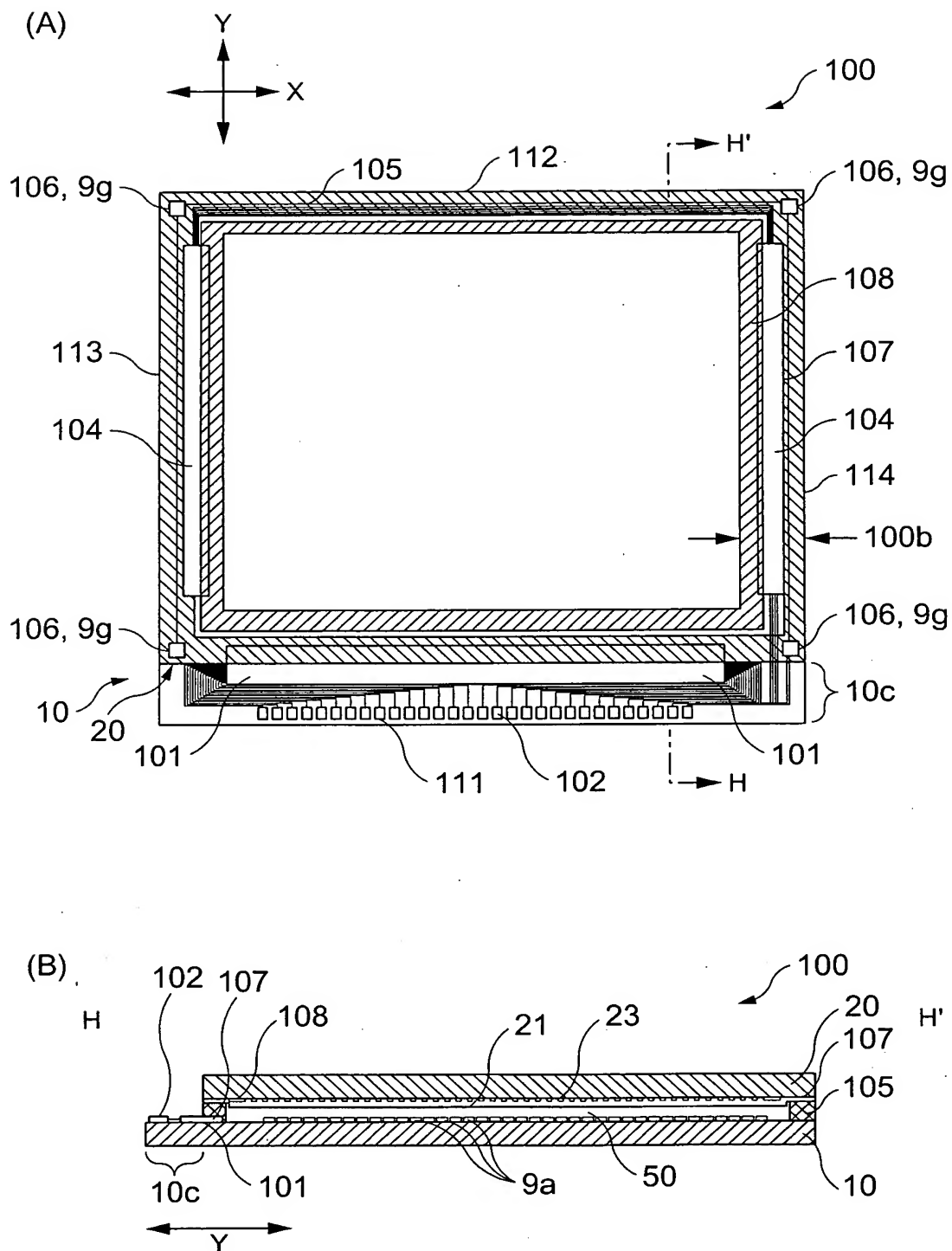


FIG. 5

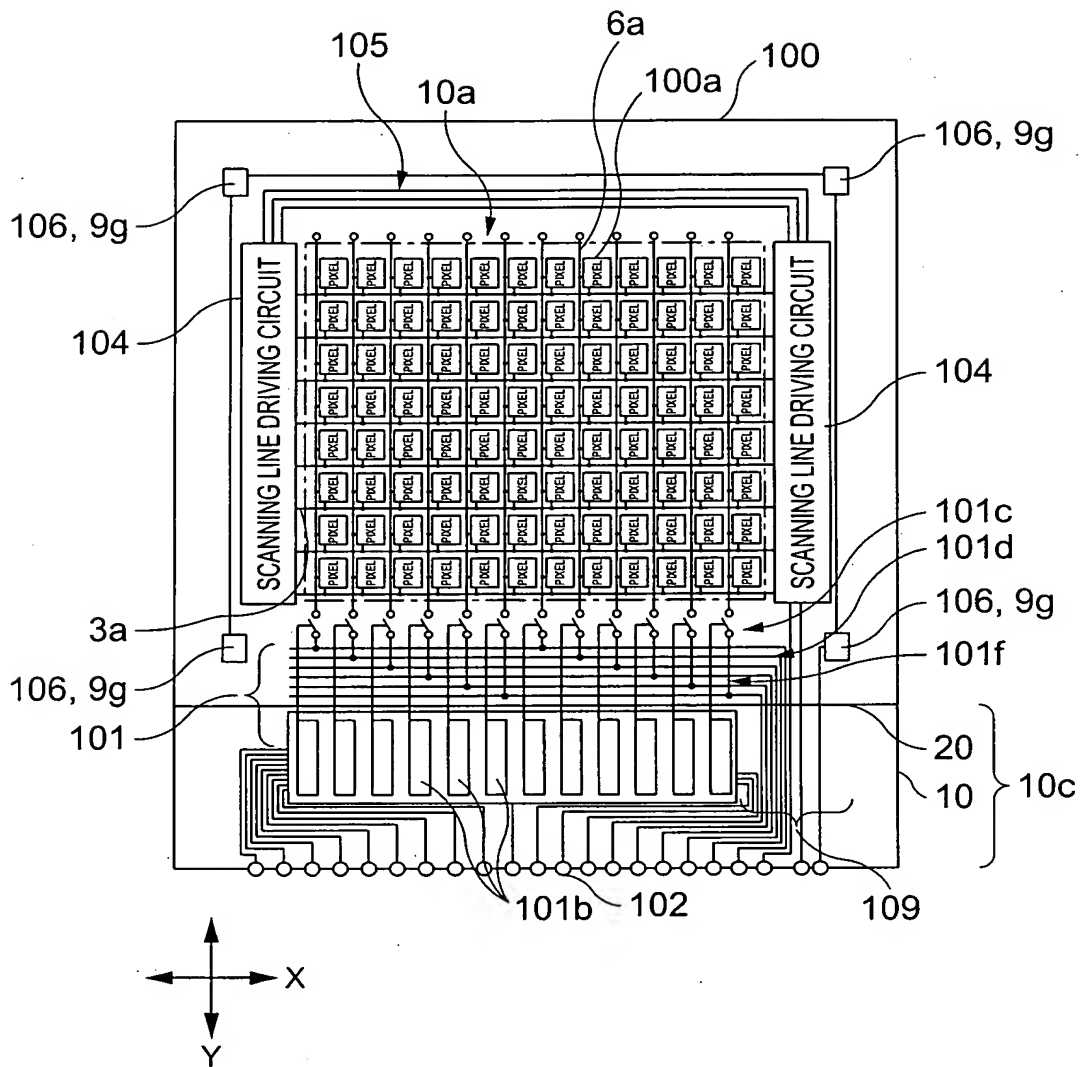


FIG. 6

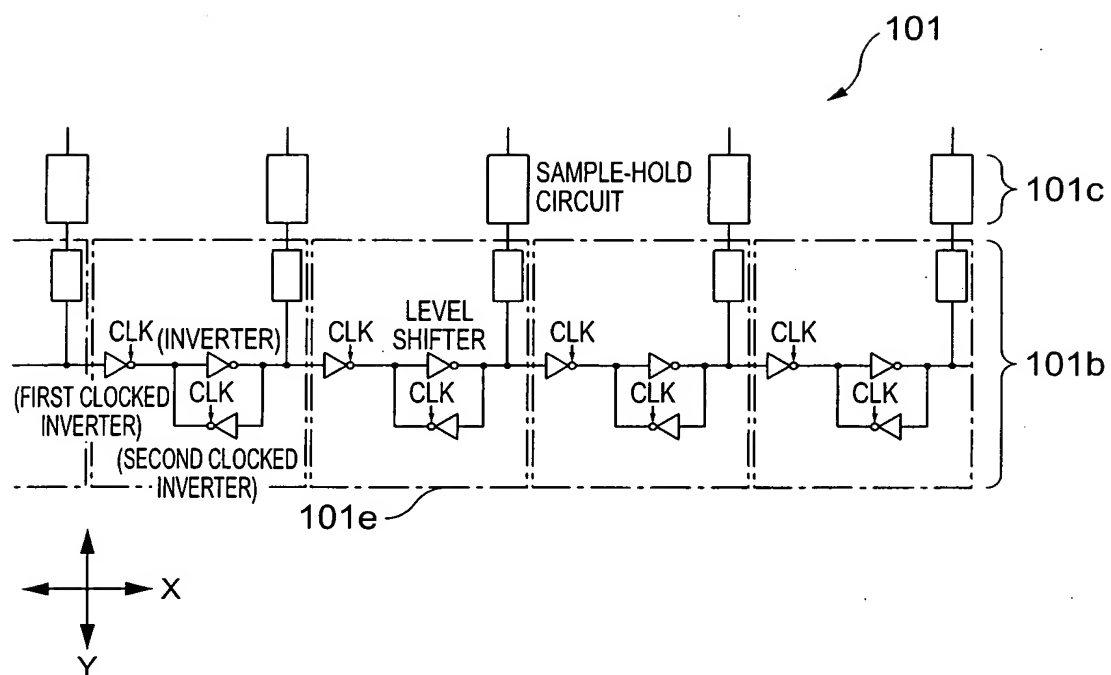


FIG. 7

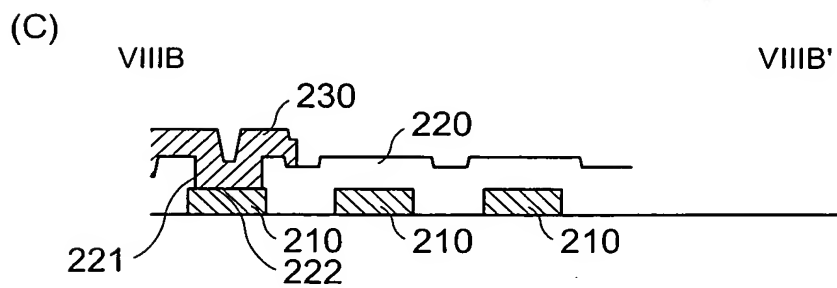
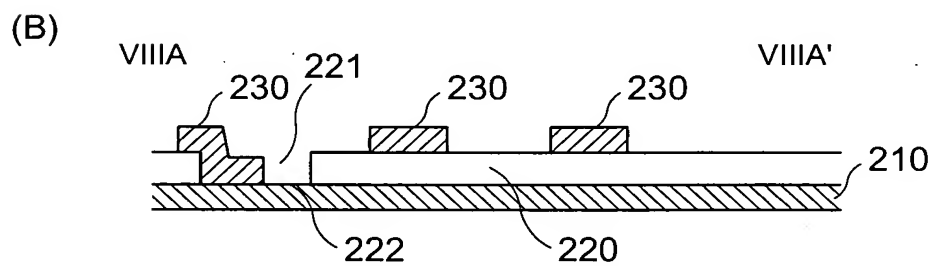
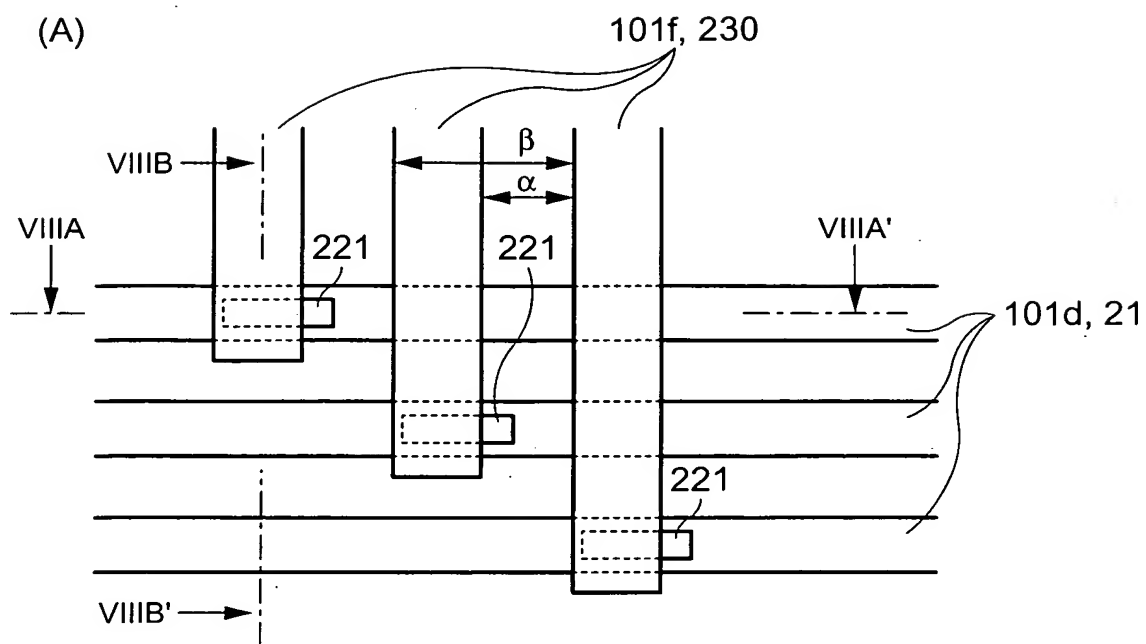


FIG. 8



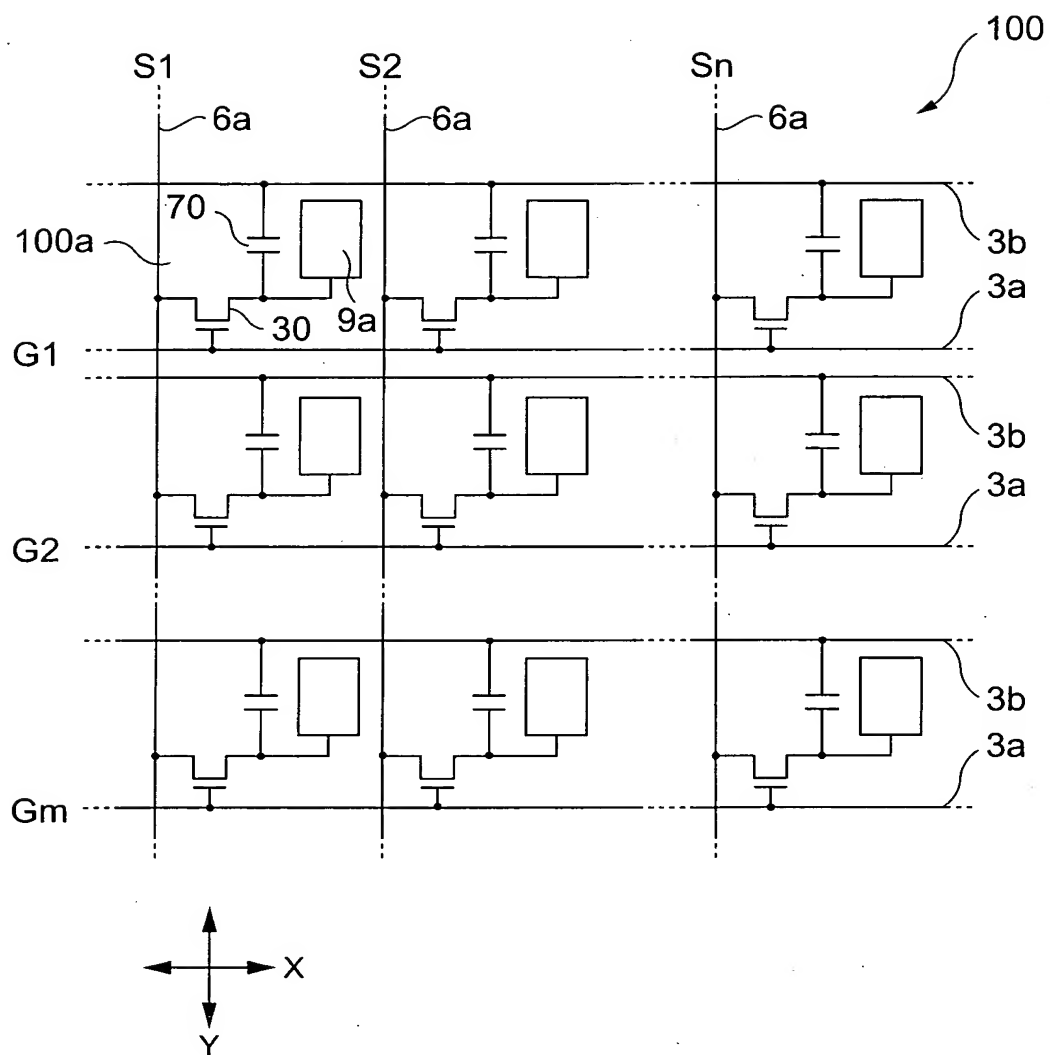


FIG. 9

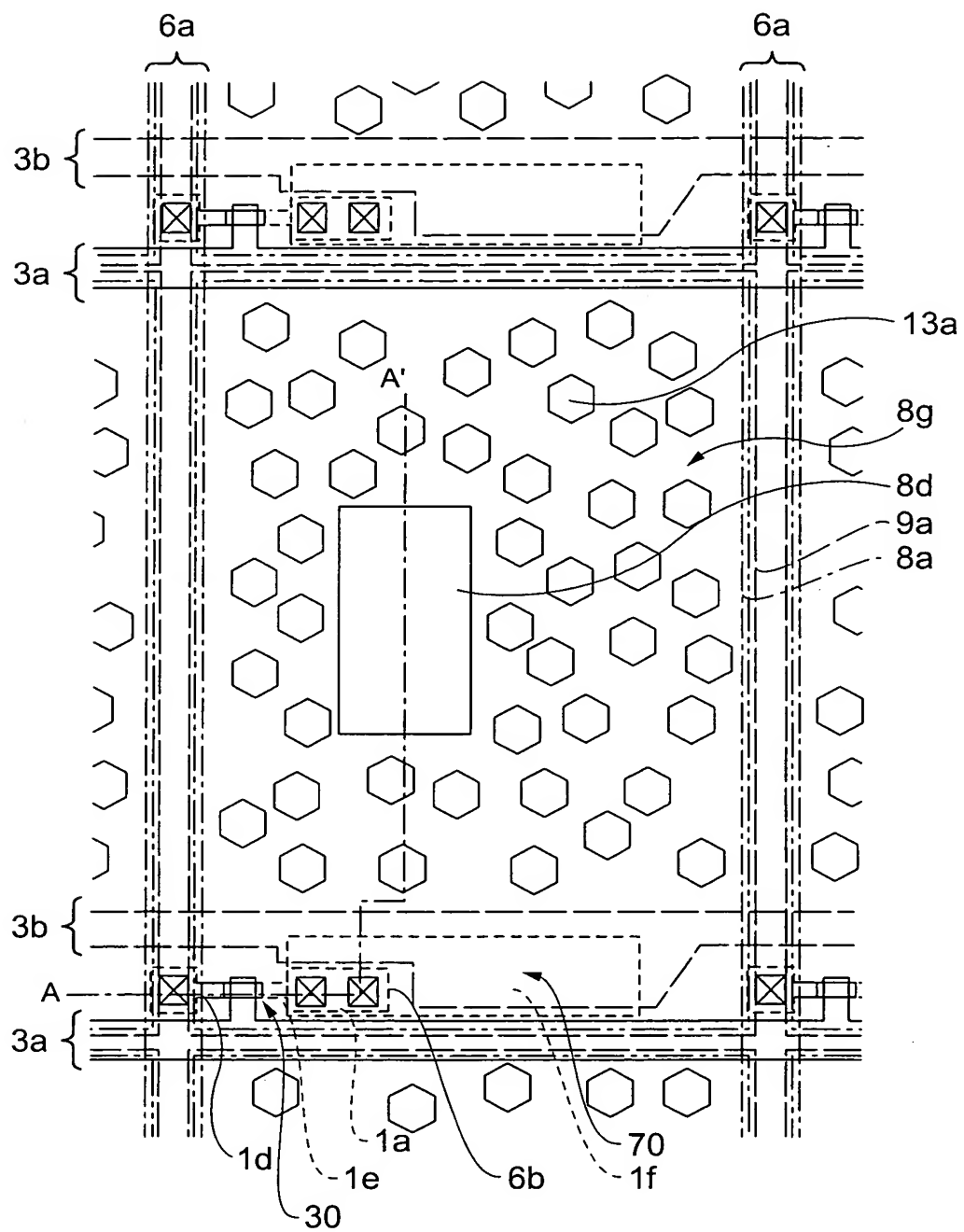


FIG. 10

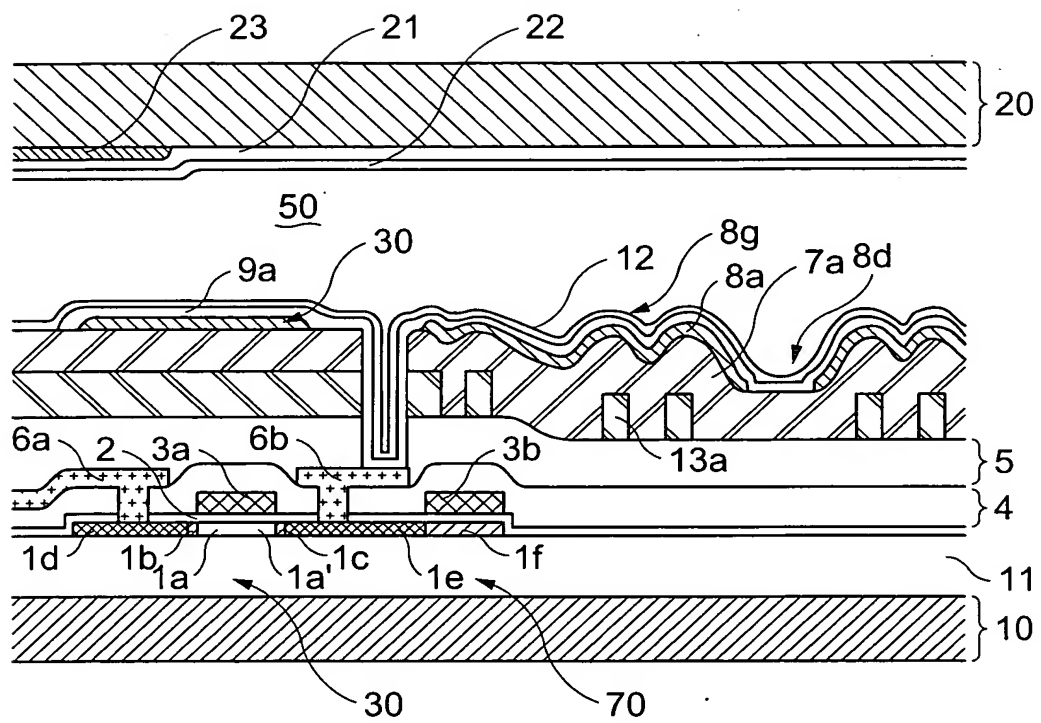


FIG. 11

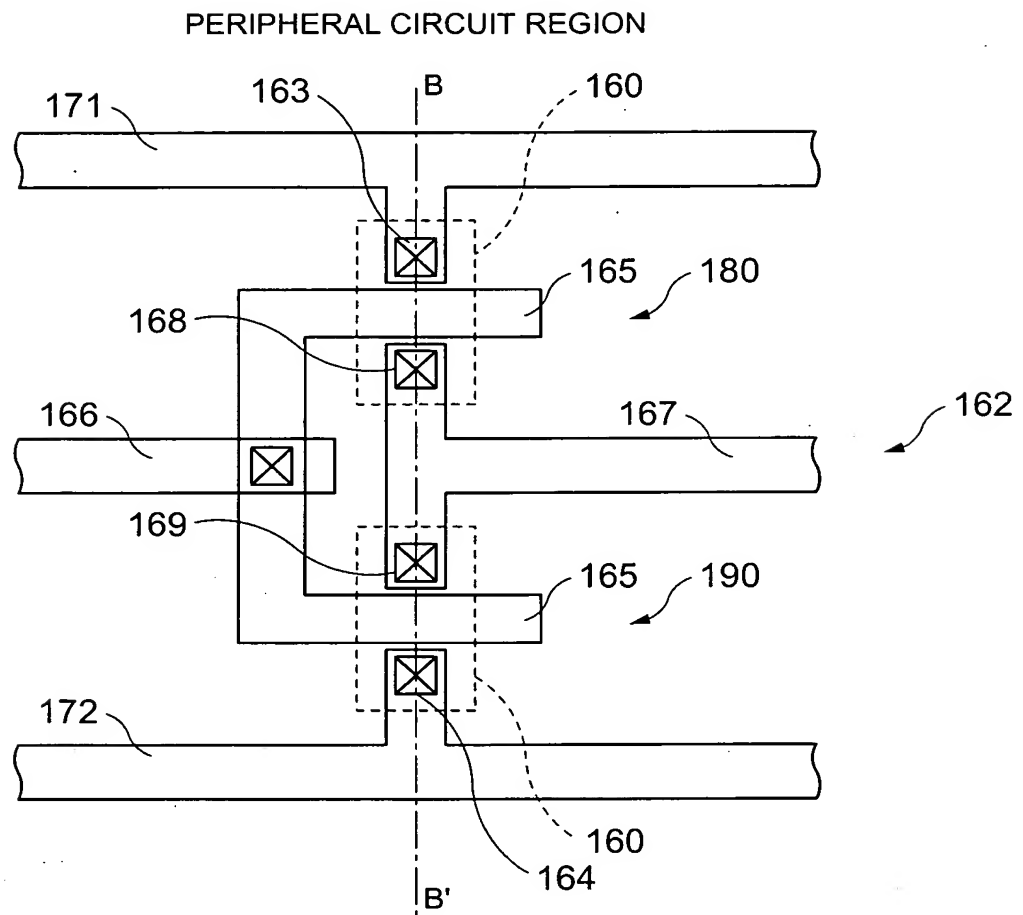


FIG. 12

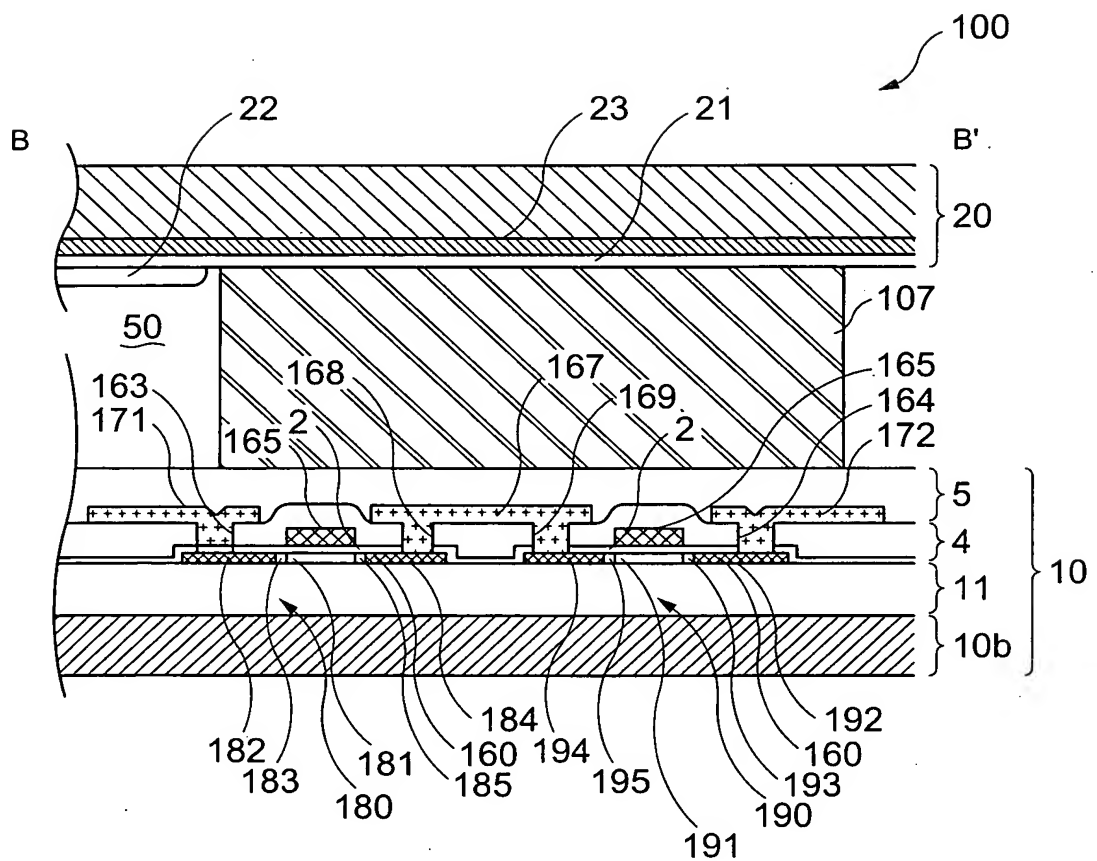


FIG. 13



FIG. 14

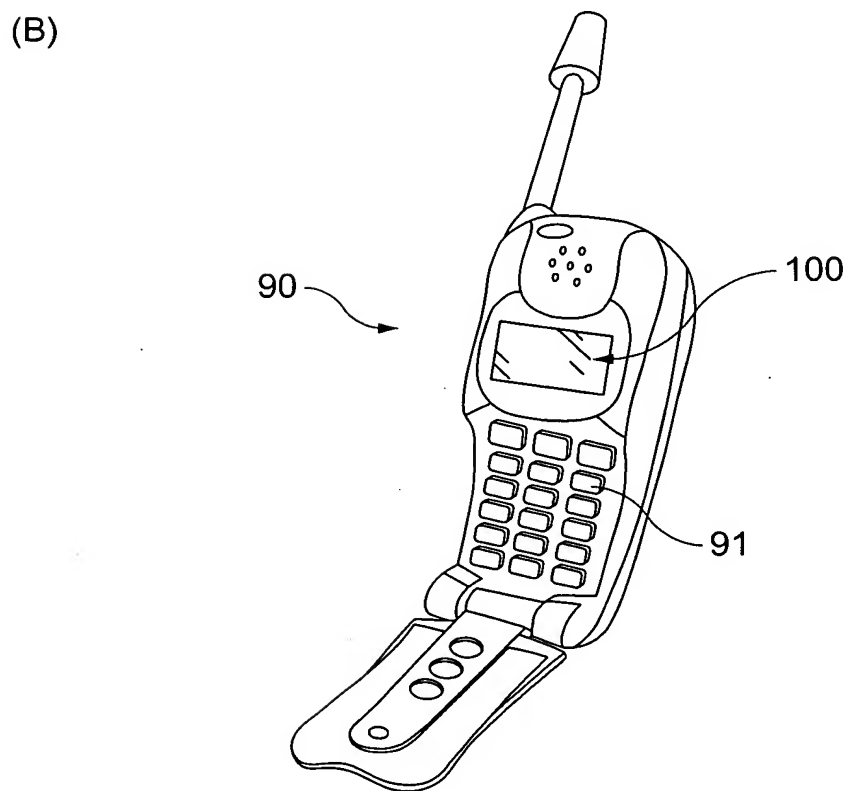
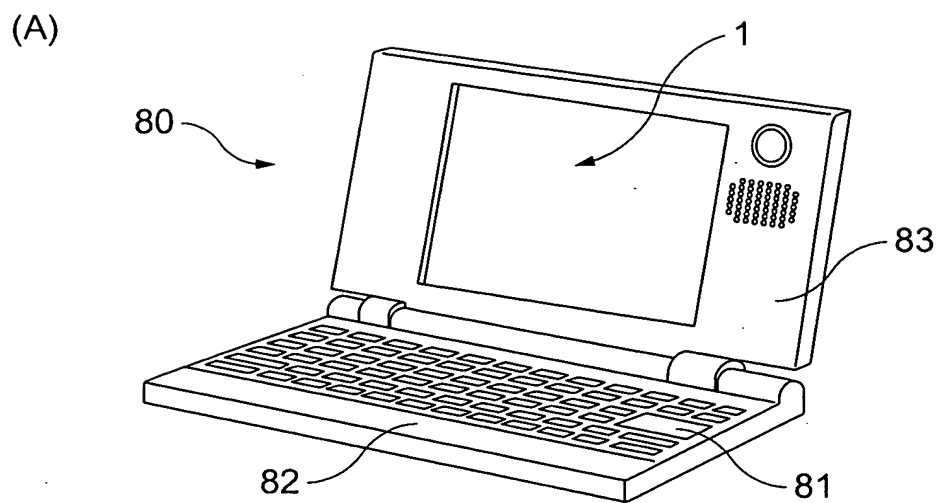
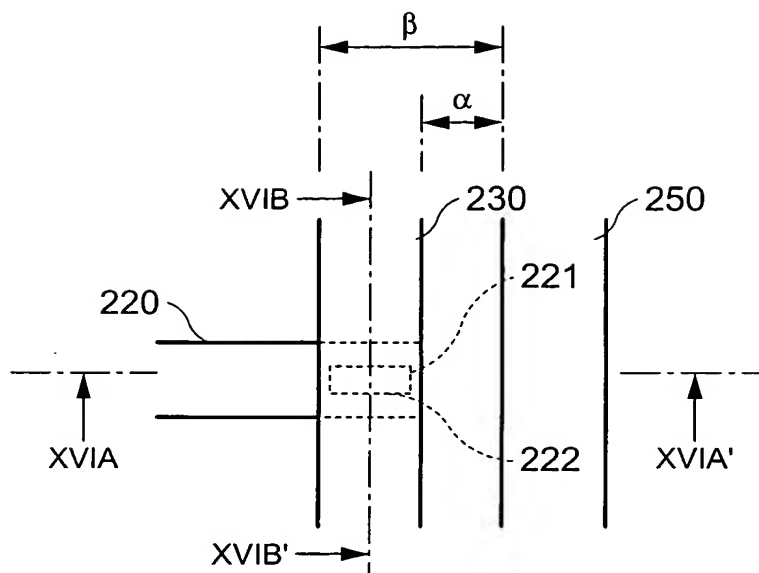
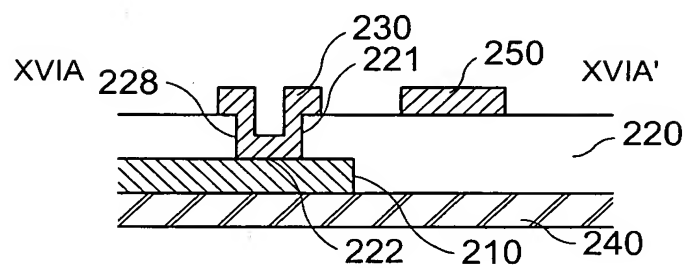


FIG. 15

(A)



(B)



(C)

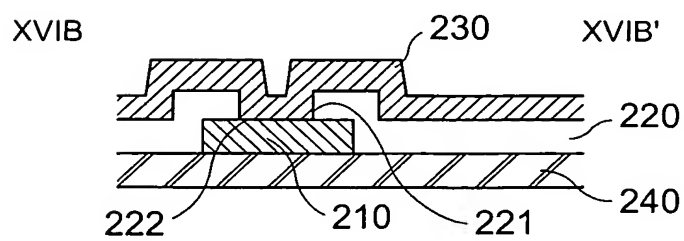


FIG. 16